

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Errors
1	BRS	0	die with op-amp and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:16		0
2	BRS	2	die with op-amp and center	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:27		0
3	BRS	11	die with op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 18:39		0
4	BRS	156	chip with op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:36		0
5	BRS	138	chip with follow\$5 with stress\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:37		0
6	BRS	1	chip with follow\$5 with stress\$4 with center	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:38		0
7	BRS	2	die with follow\$5 with stress\$4 with center	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:40		0
8	BRS	153	current near mirror with (op-amp or op adj amp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 17:04		0
9	BRS	10	current near mirror with (op-amp or op adj amp) and die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:50		0
10	BRS	18	current near mirror with (die or chip) and (op-amp or op adj amp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 16:52		0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
11	BRS	13	current near mirror same (op-amp or op adj amp) same (die or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 17:07			0
12	BRS	6	current near mirror with (op-amp or op adj amp) same (die or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 17:05			0
13	BRS	5	current near mirror same (op-amp or op adj amp) same (die or chip) and offset near volt\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/21 17:08			0
14	BRS	1	die with op-amp and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 16:46			0
15	BRS	12	die and op-amp and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 16:47			0
16	BRS	22	die and op adj amp and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:08			0
17	BRS	19	die and op adj amp and mirror and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:02			0
18	BRS	16	die and op adj amp and mirror and stress and center	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 16:51			0
19	BRS	3	die and op adj amp and mirror and stress not (die and op adj amp and mirror and stress and center)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:04			0

	Type	Hits	Search Text	DBs	Time Stamp	C	o	m	m	e	n	t	s	E	r	r	o	r	s
20	BRS	4	die and op adj amp and current near mirror and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:05														0
21	BRS	4	stress die and op adj amp and current near mirror and pack\$6 and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:06														0
22	BRS	14	stress (center or middle or inner) near die and op adj amp and mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:09														0
23	BRS	14	(center or middle or inner) near die and op adj amp and mirror and current	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:14														0
24	BRS	48 1	(center or middle or inner) with mirror with current	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:15														0
25	BRS	29	(center or middle or inner) with mirror with current and op adj amp	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:16														0
26	BRS	18	(center or middle or inner) with mirror with current and op adj amp and die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:18														0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
27	BRS	2	(center or middle or inner) and mirror near current and op adj amp and die and	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/07 17:19			0
28	BRS	96	(substrate or wafer) with (op-amp or op adj amp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:18			0
29	BRS	123	(substrate or wafer or die) with (op-amp or op adj amp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:19			0
30	BRS	28	(substrate or wafer or die) with (op-amp or op adj amp) and (center or middle or mid adj point or inner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:25			0
31	BRS	4	(substrate or wafer or die) with (op-amp or op adj amp) and current near mirror and (center or middle or mid adj point or inner)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 01:28			0
32	BRS	22	(substrate or wafer or die) with (op-amp or op adj amp) and current near mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 22:41			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Info
33	BRS	7	("3477031" "3714527" "3729660" "3823354" "3863331" "3995304" "4025941").PN.	USPAT	2004/07/23 22:39			0
34	BRS	1	(substrate or wafer or die) near (op-amp or op adj amp) and current near mirror	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 22:43			0
35	BRS	8	(substrate or wafer or die) with (op-amp or op adj amp) and current near mirror and input adj offset	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 22:47			0
36	BRS	0	(substrate or wafer or die) and (op-amp or op adj amp) and current near mirror and input adj offset and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 23:00			0
37	BRS	15	(substrate or wafer or die) and (op-amp or op adj amp) and input adj offset and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 22:48			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
38	BRS	14	(substrate or wafer or die) and current near mirror and input near offset near volt\$6 and stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 23:34			0
39	BRS	3	6104231.URPN.	USPAT	2004/07/23 23:30			0
40	BRS	10	("3882725" "3895221" "3944920" "4371837" "4521727" "4734594" "4760285" "4857842" "5055768" "5159277").PN.	USPAT	2004/07/23 23:31			0
41	BRS	18	(substrate or wafer or die or chip) and current near mirror with stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 23:35			0
42	BRS	15	(substrate or wafer or die or chip) and current near mirror with stress and amplifier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 00:14			0
43	BRS	2	(substrate or wafer or die or chip) with current near mirror with (cent\$6 or mid\$6) and amplifier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:15			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error	Errors
44	BRS	17	(substrate or wafer or die or chip) with amplifier with circuit and current near mirror with (cent\$6 or mid\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:11			0
45	BRS	7	(substrate or wafer or die or chip) with (operational adj amplifier or op-amp or op adj amp) with circuit and current near mirror with (cent\$6 or mid\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 15:12			0
46	BRS	7	(substrate or wafer or die or chip) with (operational adj amplifier or op-amp or op adj amp) with circuit and current near mirror with (cent\$6 or mid\$6) and (integrat\$6 or monolith\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 16:50			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Errors
47	BRS	15	(substrate or wafer or die or chip) with (operational adj amplifier or op-amp or op adj amp) with circuit and current adj mirror near input and (integrat\$6 or monolith\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 16:52		0
48	BRS	1	5623232.URPN.	USPAT	2004/07/24 17:01		0
49	BRS	2	die with stress and op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:42		0
50	BRS	4	5777465.URPN.	IBM_TDB USPAT	2004/07/24 18:42		0
51	BRS	28	substrate with stress and op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:43		0
52	BRS	4	substrate with stress and op-amp and mirror near current	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 18:46		0
53	BRS	58 82	op-amp	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:46		0
54	BRS	34	(438/\$3).ccls. and op-amp	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:50		0
55	BRS	10	(438/\$3).ccls. and op-amp and stress	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/07/24 18:51		0

IBM_TDB